



A Step by Step Optimization of the c-Si Bottom Cell in Monolithic Perovskite/c-Si Tandem Devices

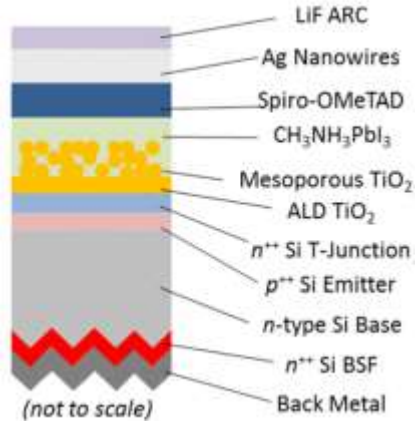
Yiliang Wu¹, Andreas Fell² and Klaus Weber¹

APSRC 2018

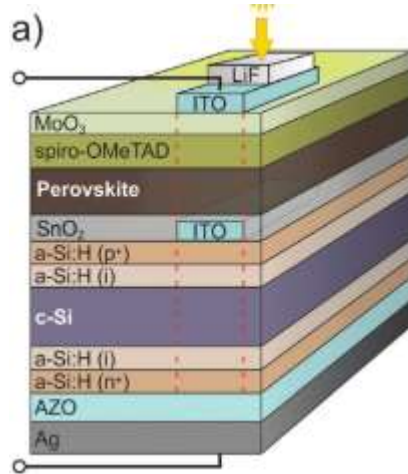
1. Research School of Engineering, Australian National University

2. Fraunhofer Institute for Solar Energy Systems

The rapid evolution

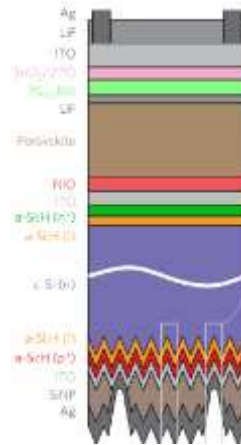


13.7%



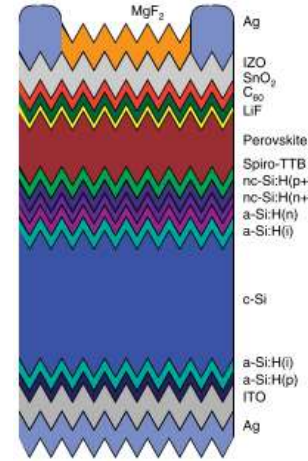
18.1%

Albrecht, S., et al. *Energy Environ. Sci.* 9 (2016)



23.6%

Bush, K., et al. *Nat. Energy* 2 (2017)



25.2%

Sahli, F., et al. *Nat. Mat.* (2018)

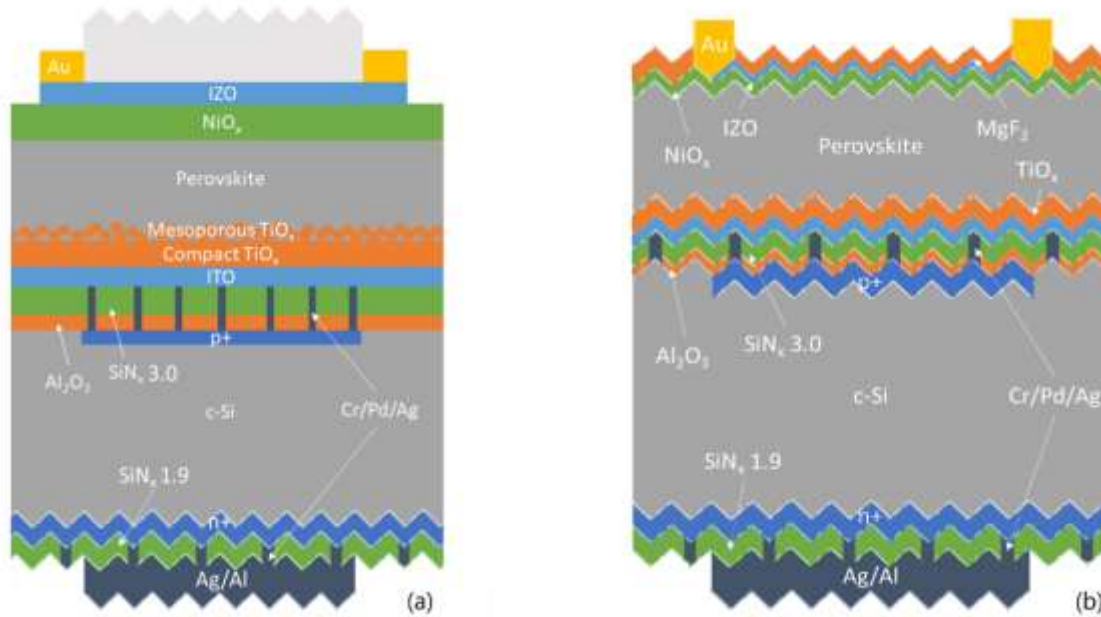


27.3%

Oxford PV, *News release.* (2018)

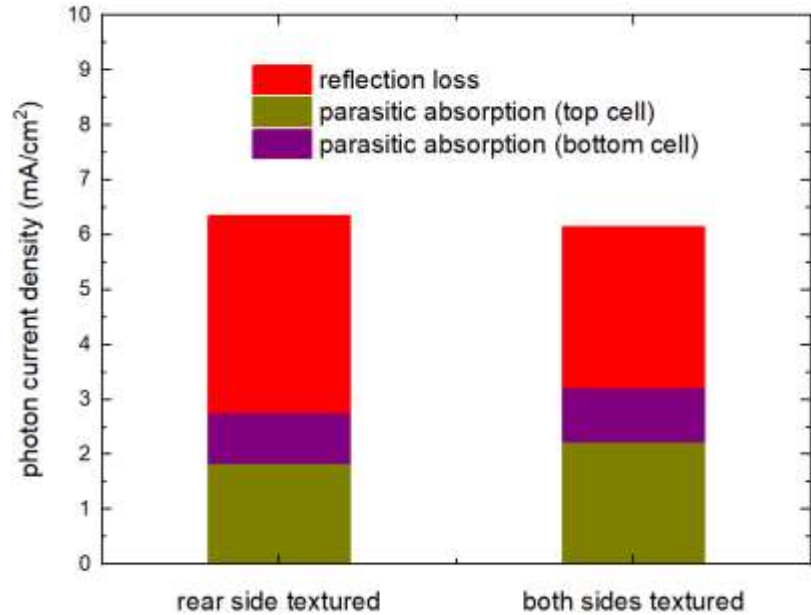
Mailoa, J., et al. *Appl. Phys. Lett.* 106 (2016)

Rear or both sides texturing?



*not to scale

Rear or both sides texturing?



		rear side textured		both sides textured	
		thickness	loss (mA/cm ²)	thickness	loss (mA/cm ²)
reflection loss	reflected		0.063		1.774
	escaped		3.538		1.166
parasitic absorption loss	silicone foil	400 μm	0.265	n/a	n/a
	Au (front finger)	100 nm	0.336	100 nm	0.262
	MgF ₂	n/a	n/a	100 nm	0.627
	IZO	40 nm	0.609	40 nm	0.698
	NiO	50 nm	0.624	50 nm	0.653
top cell	perovskite	310 nm	19.98	310 nm	20.08
	ms-ITO ₂	60 nm	0.0001	n/a	n/a
	cp-TiO ₂	50 nm	0.001	50 nm	0.001
parasitic absorption loss	ITO	20 nm	0.241	20 nm	0.340
	SiN _x /Al ₂ O ₃	50/10 nm	0.144	50/10 nm	0.140
	c-Si	280 μm	19.99	290 μm	20.08
bottom cell	Si ₃ N ₄	70 nm	0.006	70 nm	0.004
	Ag/Al	100/700 nm	0.540	100/700 nm	0.486

Rear or both sides texturing?

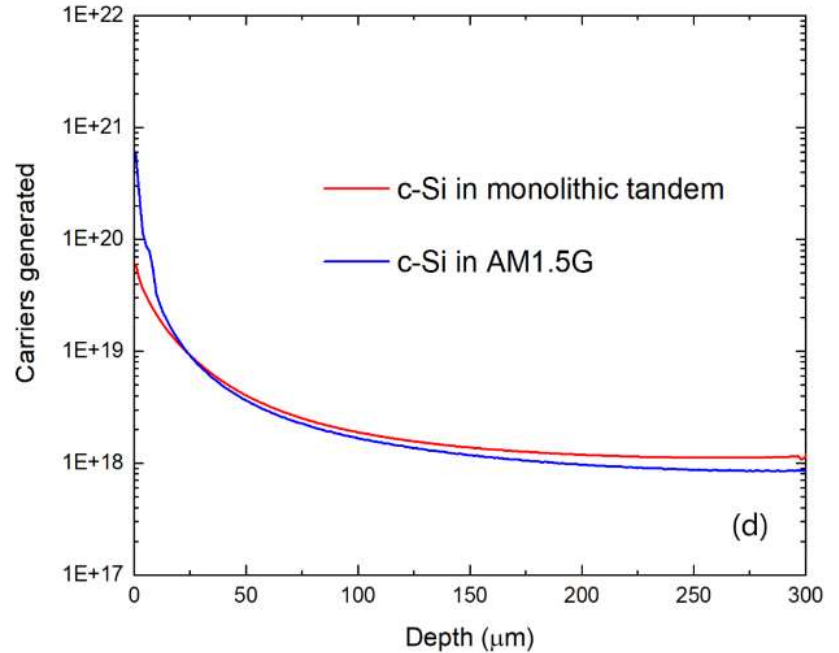
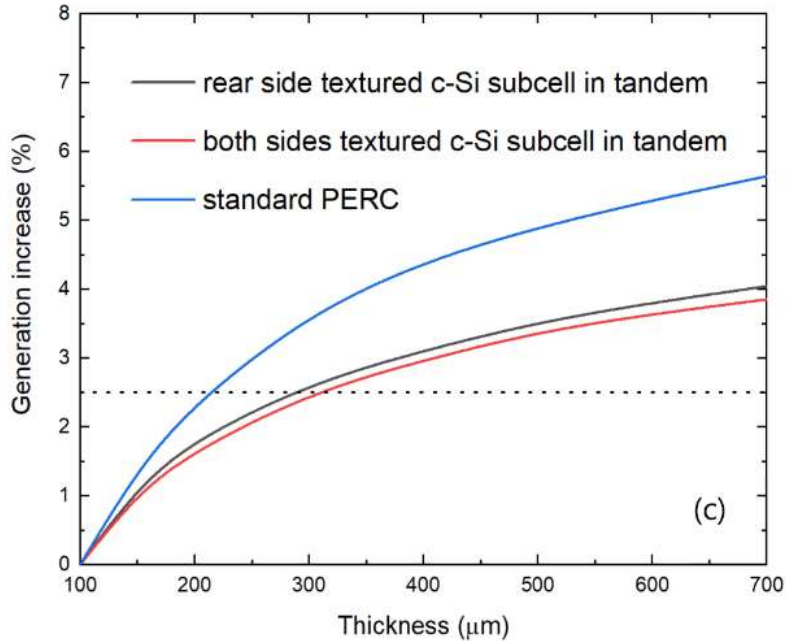
Both sides

Deposition of perovskite cell on textured surface can be problematic

Rear side only

- Refractive index of TCO and charge transport must be carefully managed to reduce the escaped light
- An anti-reflection foil must be implemented, but can be replaced by structured glass for module application

What has changed?

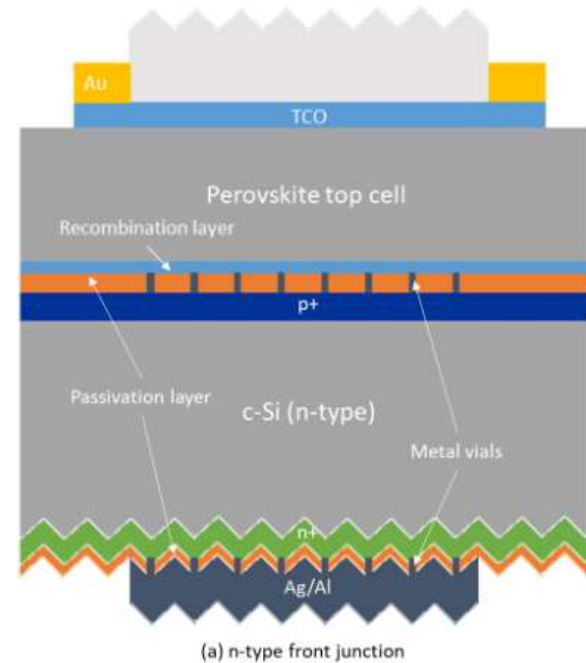
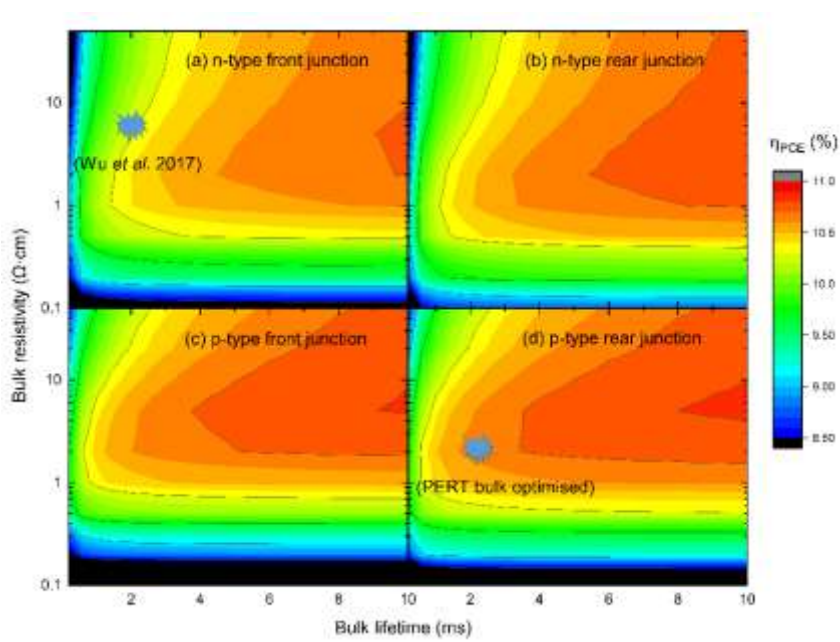


What has changed?

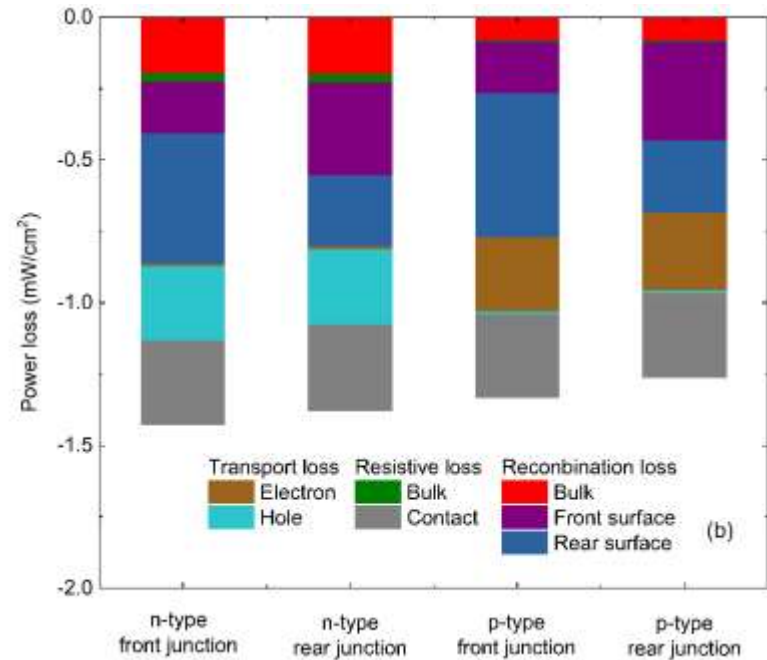
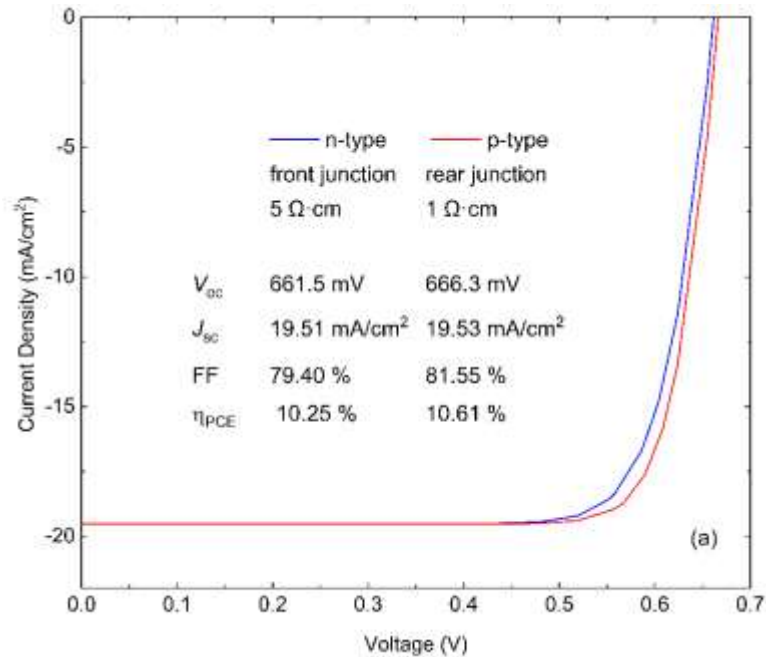
- Increased wafer thickness for tandem application
- Significantly more uniform generation profile

Simulated result by  Quokka3

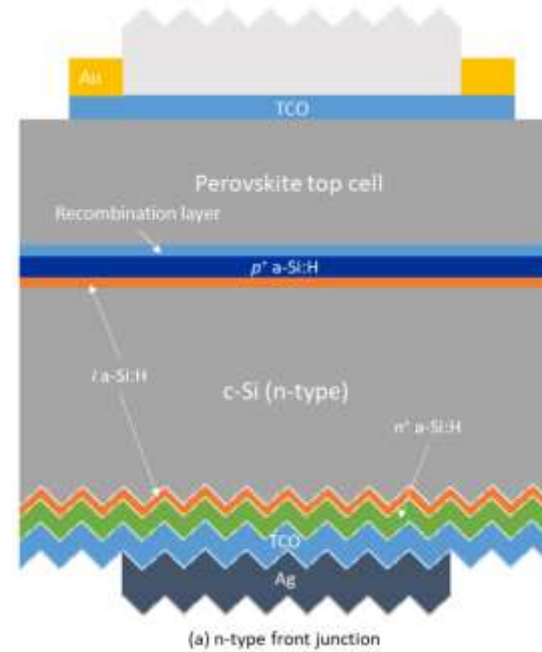
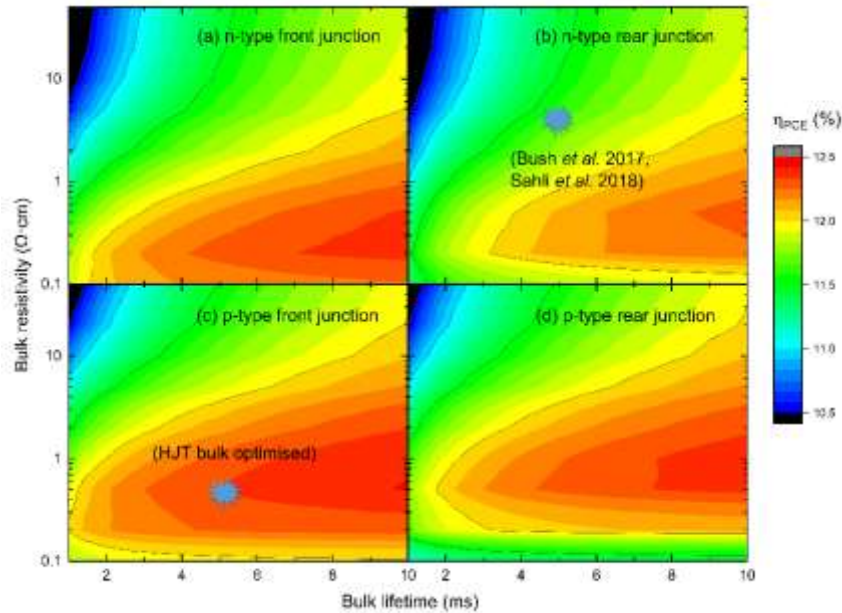
c-Si bulk optimization (PERT)



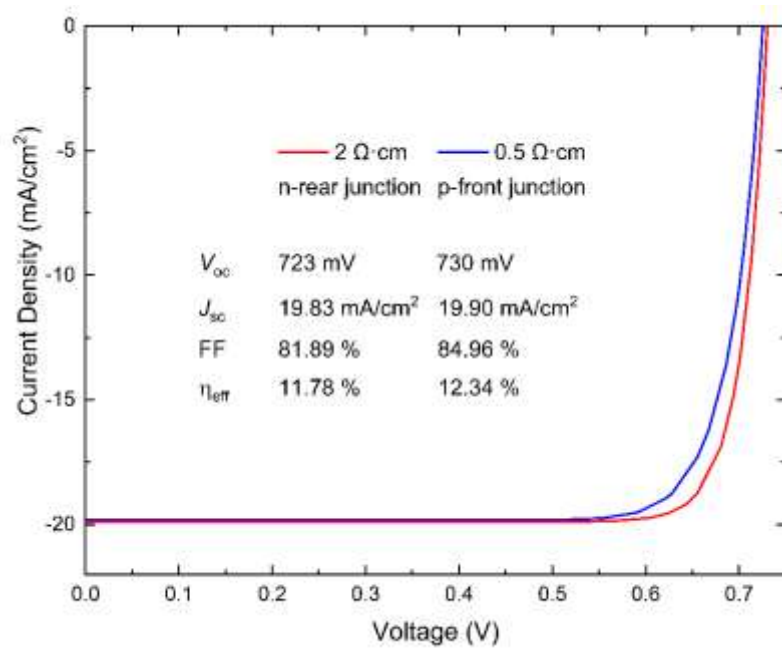
c-Si bulk optimization (PERT)



c-Si bulk optimization (HJT)



c-Si bulk optimization (HJT)



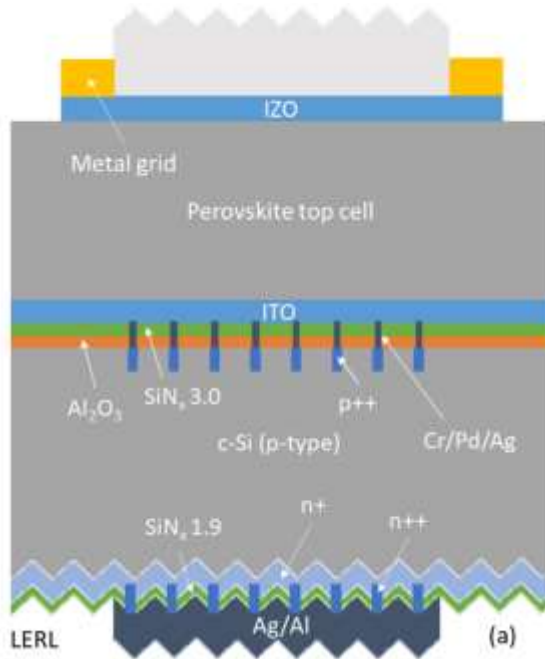
Parameters	n-front junction	n-rear junction	p-front junction	p-rear junction				
$\tau_{bulk\ fixed}$ (ms)			1 ~ 10					
R_{bulk} ($\Omega \cdot cm$)			0.1 ~ 50					
R_{sheet} (Ω/\square)			120					
$\rho_{contact}$ ($m\Omega \cdot cm^2$)			5					
Side	Front	Rear	Front	Rear	Front	Rear	Front	Rear
$J_{0-contacted}$ (fA/cm ²)	2	3	2	3	2	3	2	3

c-Si bulk optimization

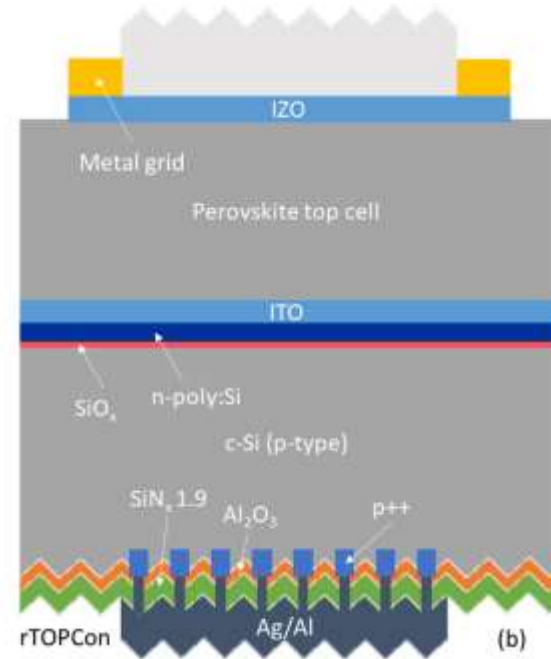
- p-type wafers are more suitable
- relatively low resistivity
- front or rear junction is not very important

LERL and rTOPCon

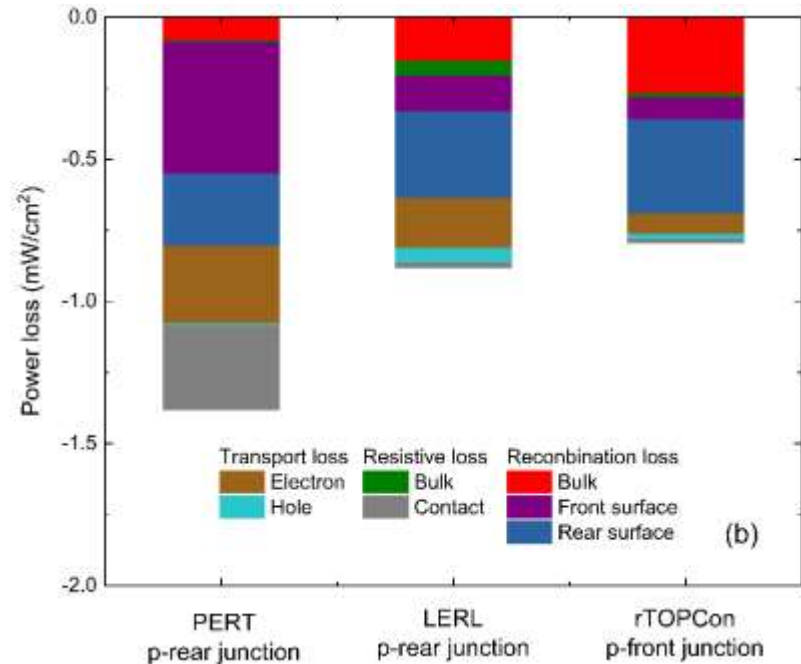
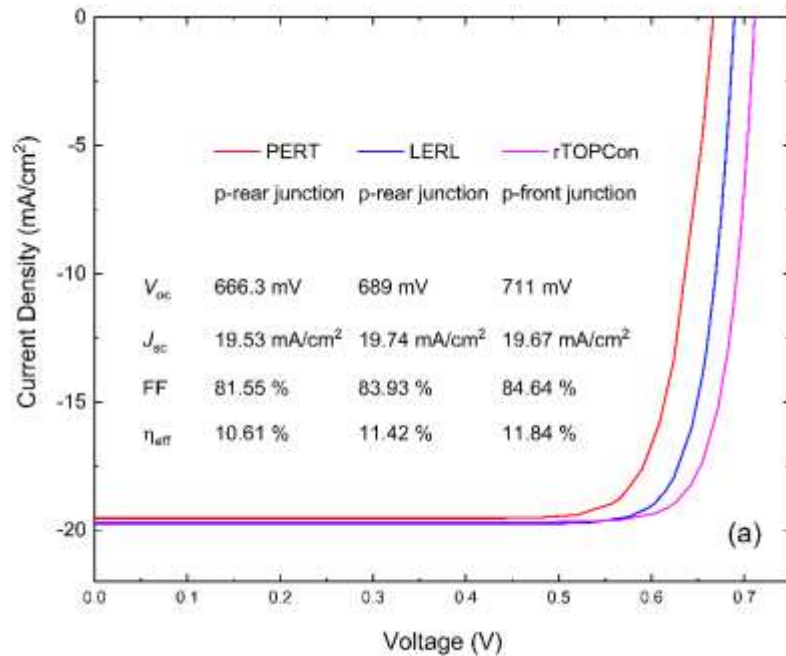
n-i-p



p-i-n



LERL and rTOPCon



Conclusions

- Rear and double sided texturing show similar generation
- p-type wafers are found to be a more suitable candidate for fabricating high efficiency monolithic tandem device
- LERL and rTOPCon are proposed for better bottom cell structures

Acknowledgements

